

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS EXPRESS MAIL IN AN ENVELOPE ADDRESSED TO: U.S. PATENT AND TRADEMARK OFFICE, P.O. BOX 2327, ARLINGTON, VA 22202. APPLICANT AND/OR ATTORNEY REQUESTS THE DATE OF DEPOSIT AS THE FILING DATE.

May 13, 2002

(Date of Deposit)

June M. Mitchell 5/13/02  
(Signature & Date)  
June M. Mitchell

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of :

May 13, 2002

Clément J. Fortin, et al. :

Examiner:

Serial No. :

Art Unit:

Filed: Herewith :

IBM Corporation  
Intellectual Property Law  
Dept. N50/040-4  
1701 North Street  
Endicott, New York 13760

Title: SMT PASSIVE DEVICE NOFLOW  
UNDERFILL METHODOLOGY AND  
STRUCTURE :

**INFORMATION DISCLOSURE STATEMENT**

U.S. Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Sir:

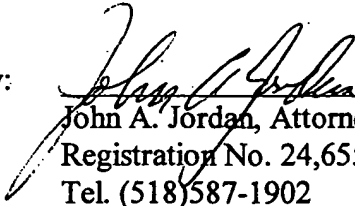
Pursuant to the duty of disclosure set forth in 37 CFR 1.56, the Applicants wish to bring to the attention of the United States Patent and Trademark Office the U.S. patents listed on the attached Form PTO-1449, and the Applicants request that these documents be made part of the record. Copies of these patents are enclosed.

In citing the above documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that a search has been made, that better art than that listed is not available, or that other art is not applicable.

Respectfully submitted,

Clément J. Fortin, et al

By:

  
John A. Jordan, Attorney  
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LRF/JAJ

FORM PTO-1449 (Modified)

ATTY. DOCKET NO.

SERIAL NO.

LIST OF PATENTS AND PUBLICATIONS FOR  
APPLICANT'S INFORMATION  
DISCLOSURE STATEMENT

END920020027US1

APPLICANT: CLÉMENT J.  
FORTIN, ET AL.

PAGE 1 OF 1

(Use several sheets if necessary)

FILING DATE:

GROUP:

## Reference

## US Patent Documents

## Designation

EXAMINER INITIALS		DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)
	AA	4,339,785	07/13/82	OHSAWA	361	411	04/08/80
	AB	5,085,364	02/04/92	ISHIKAWA, ET AL.	228	139	09/05/90
	AC	5,128,746	07/07/92	PENNISI, ET AL.	357	72	09/27/90
	AD	5,493,259	02/20/96	BLALOCK, ET AL.	333	182	03/06/95
	AE	5,529,957	07/25/96	CHAN	437	250	04/06/95
	AF	5,814,401	09/29/98	GAMOTA, ET AL.	428	343	02/04/97
	AG	6,071,371	06/06/00	LEONARD, ET AL.	156	297	02/02/98
	AH	6,202,917B1	03/20/01	WEAVER, ET AL.	228	180	08/19/98
	AI						
	AJ						
	AK						

Foreign Patent  
Documents

	AL	JP401100993A	04/19/89	AKIYAMA	H05K3	34	10/14/87
	AM						
	AN						
	AO						

OTHER ART (Including  
Author, Title, Date,  
Pertinent Pages, etc.)AP AMICON® E 1350 Series, "No Flow-Fluxing Underfill Encapsulants for Flip Chip Devices",  
Emerson & Cuming, Specialty Polymers.

AQ SE-CURE® 9101 "Reflow Encapsulant", Kester Solder, Polymer Products Group.

AR STAYCHIP™, NUF-DP0071 - No Flow Underfill, Developmental Product Information.

AS DEXTER, HYSOL® FF 2200, "Reflow Encapsulant".

AT DEXTER, HYSOL® FluxFill™ 2000, "Reflow Encapsulant".

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered,  
whether or not citation is in conformance  
with MPEP 609. Draw line through citation  
if not in conformance and not considered.  
Include copy of this form with next  
communication to applicant.